



WORLD'S FIRST PHOTONICS PACKAGING PILOT LINE FOR PHOTONIC INTEGRATED CIRCUITS

New 15.5M Euro PIXAPP Photonics Packaging Pilot Line to Drive EU Growth and Competitiveness in Global Photonics Industry

Brussels, 30 March 2017: The European Union, in partnership with Photonics21, have funded a 15.5M Euro Pilot Line for the assembly and packaging of advanced Photonic Integrated Circuits (PICs). The Pilot Line, called PIXAPP, will establish the world's first open access PIC assembly and packaging supply chain, with capacities ranging from early stage prototyping to medium volumes. PIXAPP combines an interdisciplinary team of Europe's leading industrial and research organisations, providing users with state-of-the-art PIC assembly and packaging technologies, including optical, electrical, thermal and mechanical packaging capabilities, along with standardised test and reliability protocols. Target markets include communications, healthcare, sensors and security. PIXAPP will provide users with a single easy access point-of-contact called the Pilot Line Gateway, which is located at the Tyndall National Institute in Cork, Ireland. The Gateway is staffed by packaging experts and project managers, and will ensure users, including non-photonics experts, get fast access to PIXAPP's extensive range of advanced assembly and packaging technologies. Furthermore, PIXAPP will implement an advanced training programme, where attendees will receive lab-based training on all aspects of PIC assembly and packaging.

Speaking from the Photonics21 Annual General Meeting in Brussels, PIXAPP Pilot Line Director and Head of Photonics Packaging Research at Tyndall National Institute, Prof. Peter O'Brien said: *"The consortium involved in PIXAPP, has an unmatched record of excellence in delivering many world 'firsts' in PICs. We will establish 'best in class' PIC packaging technologies that are cost-effective and scalable to high volume manufacture. We will offer these technologies through a single easy access point, which we call the Pilot Line Gateway. Furthermore, we plan to train and educate the photonics workforce of the future by creating a unique laboratory based training programme. This training programme is a game-changer not only for the European photonics industry but also global photonics."*

"In the past, it has been very expensive to manufacture high volumes of PICs, and more expensive and challenging again to package them. This is creating a bottleneck for production, which is impacting the potential for growth in the photonics industry. I am confident that our leadership will deliver market success for Europe and drive our competitiveness across the communications, medical, automotive, energy, safety and defence sectors globally," said Jose Pozo, Director of Technology and Innovation at EPIC (European Photonics Industry Consortium).

For more information, see www.pixapp.eu



PIXAPP Presentation and Booth at Photonics21 Annual Meeting in Brussels on 29 March 2017